

PRODUCT INFORMATION

FEATURES

- Complete single-chip channelized DS3 solution
- RISC processor with royalty-free DD-AMPS[™] firmware (Drivers, Data link, Alarms, Messaging, Performance/configuration objects, and Signaling)
- Host communication via royalty-free, message-based, POSIX-compatible API
- Integrated 672 x 4,096-channel DS0 cross connect supports grooming, broadcast, off-bus hairpinning, and bonding
- Integrated DS1/E1 cross connect
- Integrated G.747 function to Mux/De-Mux 21 E1s to/from DS3.
- 28 DS1 or 21 E1 line interfaces or 1 DS3 line interface
- Combination of unframed DS1/E1, transmission DS1/E1, link channel interface (LCI), and either MVIP or H.100/H.110 as terminal side interfaces
- Selectable DS3 clear channel functionality
- On-chip maintenance of 15-minute performance objects per IETF RFCs 2495, 2496, and 2494.
- Support 2 SS7 and 28 ISDN-PRI signaling channels
- Two DS1/E1 monitor ports for monitoring any DS1/E1 clock and data
- Test Access Port (IEEE 1149.1 boundary scan)
- +3.3 volt input/output leads, +5 volt tolerant
- +3.3 volt and +1.8 volt power supplies
- 456-lead plastic ball grid array package (27 mm x 27 mm); pin- and API-compatible with T3BwP (TXC-06826)

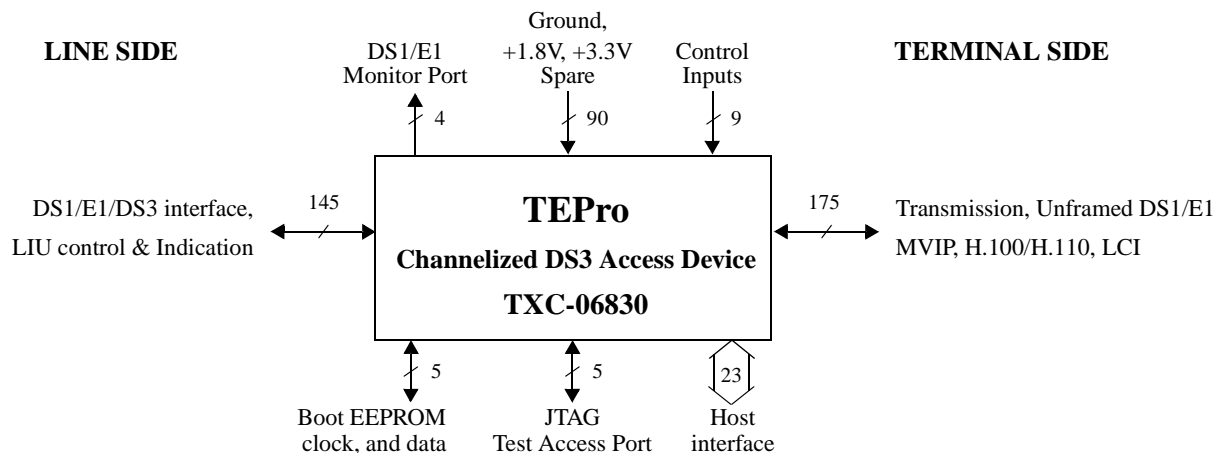
DESCRIPTION

TEPro[™] (TXC-06830) is a RISC processor-based device that supports the requirements of next-generation channelized DS3 access systems. TEPro integrates an M13 multiplexer, G.747 Mux/De-Mux framer, 28 DS1 / 21 E1 framers, T1/E1 cross connect and a 672 x 4,096-channel DS0 cross connect with an embedded high-performance microprocessor to provide a complete channelized DS3 solution on a single chip. The embedded processor firmware handles device drivers, data links, alarms, messaging, MIB performance objects, and signaling functions and allows communication to an external host via high-level API messages. The firmware is provided by TranSwitch and loaded from an external serial EEPROM at device boot-up.

The TEPro can be configured to support a variety of modes of operation, which allows for design flexibility. TEPro supports a combination of unframed DS1/E1, transmission DS1/E1 and H.100/H.110 bus or MVIP interfaces on the terminal side and either DS3 or DS1/E1 on the line side. For TDM applications, all 672 DS0 channels can be switched to any of the 4,096 H.100/H.110 bus channels. The TEPro can also be enabled to provide DS3 C-bit parity for unchannelized services. The on-chip firmware provides the control and management plane functionality to the host to configure, control and monitor all DS3, DS1, E1, DS0 and digital cross connect functions. The standards-based MIB functionality is provided for network management.

APPLICATIONS

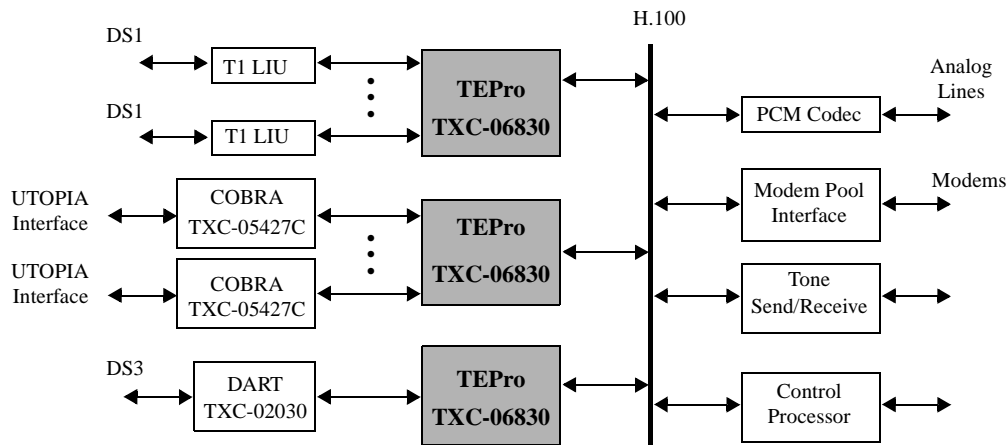
- T-carrier termination equipment: muxes, inverse muxes, cross connects, groomers
- CT (Computer Telephony) network interface boards
- VoP (Voice over Packet/Cell) gateways
- MSADs (Multi-Service Access Devices)
- DSLAMs (Digital Subscriber Loop Access Multiplexers)
- ECUs (Echo Cancellation Units)



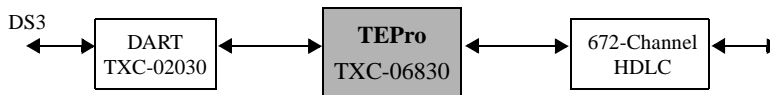
Copyright © 2002 TranSwitch Corporation
 TEPro is a trademark of TranSwitch Corporation
 TranSwitch and TXC are registered trademarks of TranSwitch Corporation
 MVIP is a registered trademark of GO-MVIP, Inc.
 SLC is a registered trademark of AT&T

Document Number:
 TXC-06830-MC
 Ed. 1, April 2002

APPLICATION DIAGRAMS



Telephony Application



DS3 Remote Access Concentrator Application

RELATED PRODUCTS

- TXC-02030 Advanced E3/DS3 Receiver/Transmitter VLSI Device (DART)
- TXC-03103 Quad T1 Framer-Plus VLSI Device (QT1F-Plus)
- TXC-03305 DS3/DS1 Mux/Demux VLSI Device (M13X)
- TXC-03452B Level 3 Mapper VLSI Device (L3M)
- TXC-03453 Triple Level 3 Mapper VLSI Device (TL3M)
- TXC-04222 21/28 Channel Dual Bus High Density mapper VLSI Device (TEMx28)
- TXC-05150 Cell Delineation Block VLSI Device (CDB)
- TXC-05427C CONSTANT Bit Rate ATM Adaptation Layer 1 VLSI Device (COBRA)
- TXC-06101 SONET STS-1 Overhead Terminator (PHAST-1)
- TXC-06103 STM-1/STS-3/STS-3c SDH/SONET Overhead Terminator with Telecom Bus Interface VLSI Device (PHAST-3N)

FURTHER INFORMATION

Contact TranSwitch for technical and ordering information on these products, including details of available operational firmware.

TranSwitch reserves the right to make changes to the product(s) or circuit(s) described herein without notice. No liability is assumed as a result of their use or application. No rights under any patent accompany the sale of any such product or circuit.

Document Number:
TXC-06830-MC
Ed. 1, April 2002